Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

Product information in this catalog is as of October 2008. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or usage of the Products.

Please note that Taiyo Yuden Co., Ltd. shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this catalog or individual specification.

- Please contact Taiyo Yuden Co., Ltd. for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of products in actual condition of mounting and operating environment before commercial shipment of the equipment.
- All electronic components or functional modules listed in this catalog are developed, designed and intended for use in general electronics equipment.(for AV, office automation, household, office supply, information service, telecommunications, (such as mobile phone or PC) etc.). Before incorporating the components or devices into any equipment in the field such as transportation,(automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network (telephone exchange, base station) etc. which may have direct influence to harm or injure a human body, please contact Taiyo Yuden Co., Ltd. for more detail in advance.

Do not incorporate the products into any equipment in fields such as aerospace, aviation, nuclear control, submarine system, military, etc. where higher safety and reliability are especially required.

In addition, even electronic components or functional modules that are used for the general electronic equipment, if the equipment or the electric circuit require high safety or reliability function or performances, a sufficient reliability evaluation check for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage.

The contents of this catalog are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN' s official sales channel").

It is only applicable to the products purchased from any of TAIYO YUDEN's official sales channel.

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Caution for export

Certain items in this catalog may require specific procedures for export according to "Foreign Exchange and Foreign Trade Control Law" of Japan, "U.S. Export Administration Regulations," and other applicable regulations. Should you have any question or inquiry on this matter, please contact our sales staff.

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積層チップNTCサーミスタ MULTILAYER CHIP NTC THERMISTORS

OPERATING TEMP.

-55~+125℃



リフロー/REFLOW

*1005TYPEを除く * Except for 1005TYPE

特長 FEATURES

・125℃保証

- ・B定数が大きく温度検知能力が優れている
- ・表裏の区別がなくバルク、テーピングでの自動装着が可能
- ・寸法はEIAJ規格に準拠
- ・内部電極構造を採用することにより、信頼性向上を実現しています

· Guaranteed up to 125°C.

- · Large B constant for higher temperature sensing capability.
- · Ideal for automatic mounting in bulk or from tapes because of front-rear symmetry.
- · Available in a standard EIA compatible case size.
- · Improved reliability due to use of internal electrodes.

APPLICATIONS 用途

- ・通信機用
- 自動車電話、携帯電話、コードレス電話ほか
- ・OA機器用 ファクシミリ、ワードプロセッサほか プリンタ、
- ・民生機器用
- ビデオ、カラーテレビ、液晶テレビ、CDプレーヤほか ・バッテリ保護回路用
- · Telecommunications equipment : mobile telephones, cellular telephones, cordless telephones, etc.
- · Office automation : printers, facsimiles, word processors, etc.
- · Consumer electronics : VCRs, color television sets, LCD television sets, CD players, etc.
- · Battery protection circuit

形名表記法 ORDERING CODE

	3		5		7		9	
形式	寸法[r	nm]	公称零負	負荷抵抗[Ω]	公称B定	数[K]	最低温度	[°C]
TB NTCサーミスタ	S0	1.0×0.5 (0402)	例		例	記号×10	5	-55
	S1	1.6×0.8 (0603)	102	1000	295	2950	_	
			154	150000	410	4100	- 10	
状	4						最高温度	[°C]
P メッキ電極品			6		8		Q	125
	包装	15 - 1 0 1 (°	抵抗許容	客差[%]	B定数許	容差[%]		
	R	<u>紙テーピング</u> 単品 (袋づめ)	F	± 1	F	±1		
	S	単四(扱うの)	G	± 2	Н	±3	-	
			н	± 3	-		当社管理	記号
			J	± 5				標準品
			К	±10				△=スペ-
ΓΒΡ	S_1	S 1	03	3 K 4	4 4	0 H	5 Q	
		S 1			4	0 H	5 Q	
Г В Р ; 1 2	S 1 3	S 1	0.3	3 K 4	4	0 H	5 Q	
B P ;		S 1			4	0 H	5 C	

1300	
TB	NTC THERMISTOR

2

Shape

Р

1.0×0.5 (0402) S0 1.6×0.8 (0603) S1

S

	4
Plated terminal	Pack
	B

ka	ging		
		Tapol Pool	

Bulk

example	
102	1000
154	150000
6	

Resistance tolerance [%]					
F	± 1				
G	± 2				
Н	± 3				
J	± 5				
К	±10				

Nomir	al B constant [K]
example	Symbol × 10
295	2950
410	4100

8	
B cons	stant tolerance[%]
F	±1
Н	±3

9	
Min. te	emperature[°C]
5	-55



Ð Internal code \bigtriangleup

Standard product △=Blank space

外形寸法 EXTERNAL DIMENSIONS



Туре	L	W	Т	e
	1.0±0.05	0.5 ± 0.05	0.5±0.05	0.25±0.10
1005 (0402)	(0.039±0.002)	(0.020 ± 0.002)	(0.020 ± 0.002)	(0.010±0.004)
	1.6±0.15	0.8±0.15	0.8±0.15	0.35±0.25
1608 (0603)	(0.063±0.006)	(0.031 ± 0.006)	(0.031 ± 0.006)	(0.014±0.010)
				Unit : mm (Inch)

R-T特性図 **R-T CHARACTERISTICS**

1005type (0402)



1608type (0603)



仕様 **SPECIFICATIONS**

	許容差(記号)Tolerance(Symbols)
R25	$\pm 1\%$ (F), $\pm 2\%$ (G), $\pm 3\%$ (H), $\pm 5\%$ (J), $\pm 10\%$ (K)
B定数	±1%(F). ±3% (H)
B Constant	±1%(F), ±3% (H)



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1005TYPE ·

形 名 Ordering Code	EHS (Environmental Hazardous	R25 [kΩ]		E数 nstant	熱時定数 Thermal time	time Dissipation	定格電力 Rated Power	備 考 Remark
	Substances)	[]	(K:25/85°C)	(K:25/50°C)	constant			
TBPS002220410H5Q	RoHS	2.2	4100	4034		0.5~2.0 m₩/℃	35mW	
TBPS0○332△410H5Q	RoHS	3.3	4100	4034				
TBPS0○472△410H5Q	RoHS	4.7	4100	4034				
TBPS00682410H5Q	RoHS	6.8	4100	4034				
TBPS0○103△410H5Q	RoHS	10	4100	4034				
TBPS0○153△410H5Q	RoHS	15	4100	4034	≦3 sec			
TBPS0○223△440H5Q	RoHS	22	4400	4336				
TBPS0○333△455H5Q	RoHS	33	4550	4483				
TBPS00473455H5Q	RoHS	47	4550	4483				
TBPS00683455H5Q	RoHS	68	4550	4483				
TBPS001040455H5Q	RoHS	100	4550	4483				
TBPS0○154△455H5Q	RoHS	150	4550	4483				

形名の○には包装 (R=テーピング、S=単品)、△には抵抗許容差記号 (J,K) が入ります。

 \bigcirc Please specify the packaging code (R : tape & reel, S : Bulk) and \triangle the resistance tolerance code (J, K).

1608TYPE -

形 名 Ordering Code	EHS (Environmental R2 Hazardous [k		B constant		熱時定数 Thermal time	熱放散定数 Dissipation	定格電力 Rated Power	備 考 Remark
5	Substances)		(K:25/85°C)	(K:25/50°C)	constant	factor		
TBPS1○470△295H5Q	RoHS	0.047	2950	2934				
TBPS1○680△295H5Q	RoHS	0.068	2950	2934				
TBPS1○101△315H5Q	RoHS	0.100	3150	3157				
TBPS1○151△315H5Q	RoHS	0.150	3150	3157				
TBPS102210410H5Q	RoHS	0.22	4100	4034				
TBPS1○331△410H5Q	RoHS	0.33	4100	4034				
TBPS10471045Q	RoHS	0.47	4100	4034				
TBPS10681410H5Q	RoHS	0.68	4100	4034				
TBPS101020410H5Q	RoHS	1.0	4100	4034				
TBPS101520410H5Q	RoHS	1.5	4100	4034				
TBPS10222410H5Q	RoHS	2.2	4100	4034		1.0∼2.5 mW/℃	63mW	
TBPS10332410H5Q	RoHS	3.3	4100	4034	≦5 sec			
TBPS104720440H5Q	RoHS	4.7	4400	4336				
TBPS106820440H5Q	RoHS	6.8	4400	4336				
TBPS101030440H5Q	RoHS	10	4400	4336				
TBPS101530460H5Q	RoHS	15	4600	4533				
TBPS1○223△460H5Q	RoHS	22	4600	4533				
TBPS1○333△460H5Q	RoHS	33	4600	4533				
TBPS104730475H5Q	RoHS	47	4750	4642				
TBPS1○683△475H5Q	RoHS	68	4750	4642				
TBPS10104475H5Q	RoHS	100	4750	4642				
TBPS10154475H5Q	RoHS	150	4750	4642				
TBPS101030344F5Q	RoHS	10	3435	3395	1			

形名の〇には包装 (R=テーピング、S=単品)、△には抵抗値許容差記号 (J, K (TBP S1 〇 103 △ 344 F 5QはF,GまたはH))が入ります。 〇Please specify the packaging code (R: tape & reel, S: Bulk) and △ the resistance tolerance code (F,G or H for TBP S1 〇 103 △ 344 F 5Q J, K for other part numbers).

特性図 ELECTRICAL CHARACTERISTICS

1005type (0402)

高温放置 High Temperature Life Test - 試験条件 Test Condition 125℃



耐湿性 Damp Heat (steady state) — 試験条件 Test Condition 85℃95%



1608type (0603)

高温放置 High Temperature Life Test 試験条件 Test Condition 125℃



耐湿性 Damp Heat (steady state) — 試験条件 Test Condition 85℃95%



<u></u>47Ω

合 100kΩ

1000hr

①最小受注単位数 Minimum Quantity

形式	製品厚み	標準数量 Standard quantity [pcs]				
Туре	Thickness [mm]	袋づめ Bulk	紙テープ Taping			
1005 (0402)	0.5 (0.020)	10000	10000			
1608 (0603)	0.8 (0.031)	2000	4000			

②テーピング材質 Tape material



③テーピング寸法 Taping Dimensions

紙テープ (8mm幅) Paper tape (0.315inches wide)



	チップ	挿入部	挿入ピッチ	テープ厚み	
形 式 Type	Chip	cavity	Insertion pitch	Tape thickness	
	A	В	F	Т	
1005 (0402)	0.65±0.1	1.15±0.1	2.0±0.05	0.8max	
1005 (0402)	(0.026±0.004)	(0.045±0.004)	(0.079±0.002)	(0.031max)	
1608 (0603)	1.0±0.2	1.8±0.2	4.0±0.1	1.1max	
	(0.039±0.008)	(0.071±0.008)	(0.157±0.004)	(0.043max)	

Unit : mm (Inch)

④リーダー部・空部 Leader and Blank portion



⑤リール寸法 Reel size



⑥トップテープ強度 Top Tape Strength

トップテープのはがし力は下図矢印方向にて0.1~0.7Nとなります。 The top tape requires a peel;-off force of $0.1 \sim 0.7 N$ in the direction of the arrow as illustrated below.



MULTILAYER CHIP NTC THERMISTORS

Specified Value		Test Methods and Remarks	
	1005 (0402)	1608 (0603)	
1. Operating Temperature Range	−55 to +125°C		
2. Storage Temperature Range	−55 to +125°C		
3. Rated Power	35mW	63mW	
4. Nominal Zero-Power Resistance	2.2~150kΩ ±5% ±10%	0.047~150kΩ ±5% ±10%	Ambient temperature:25±0.2°C Measuring electric power:0.1mW max.
5. Nominal B Constant	4100~4550K ±3%	2950~4750K ±3%	Measure the resistance at the ambient temperatures of $25\pm0.2^{\circ}$ C and $+85\pm0.2^{\circ}$ B = $\frac{\ell nR25 - \ell nR85}{1 / T25 - 1 / T85}$ T : Absolute temperature T0 : 273.15
6. Dissipation Constant (single unit)	0.5 to 2.0mW ∕ °C	1.0 to 2.5mW ∕ °C	This represents the amount of electric power required to raise the temperatur of the element by 1°C through self-heating under thermal equilibrium.
7. Thermal Time Constant (single unit)	Within 3 sec.	Within 5 sec.	This represents the amount of time for the temperature of the thermistor element to change by 63.2% of the difference between the initial temperature and the ambient temperature by the drastic change of power application into thermistor from non-zero-power to zero-power state.
8. Rated Ambient Temperature	25°C		This represents the maximum ambient temperature at which rated power could be applied
			mum permissible power.
10. Resistance to Flexure of Substrate	R25 change : Within ±3% B constant change : Within ±1%	R25 change : Within ±5% B constant change : Within ±2%	Warp : 2mm Testing board : glass-epoxy-resin substrate Board thickness : 0.8mm Pressing speed : 0.5mm / sec. Duration : 30 sec. PCB PCB PCB PCB PCB PCB PCB PCB
11. Adhesion of Terminal Electrode	R25 change : Within ±3% B constant change : Within ±1%	R25 change : Within ±5% B constant change : Within ±2%	Applied force : 5N Duration : 10sec.

MULTILAYER CHIP NTC THERMISTORS

1005 (0402) 1608 (0603) 12. Solderability At least 75% of terminal electrode is covered by new solder. At least 80% of terminal electrode is covered by new solder. According to JIS C5102 clause 8.4. Solder temperature : 230±5°C Duration : 4±1 sec. 13. Resistance to Soldering R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Refore workering : Solder temperature : 240°C Duration : 5 sec. Preheating temperature : 240°C Duration : 5 sec. 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Conditions for 1 cycle Step 1: Minimum operating temperature +0/-3°C 30±3 min Step 2: Room temperature +0/-3°C 30±3 min Step 4: Room temperature +10/-3°C 30±3 min Step 4: Room temperature +10/-3°C 30±3 min Step 4: Room temperature +10/-3°C 30±3 min Step 4: Room temperature +10/	Item	Specified Value		Test Methods and Remarks	
electrode is covered by new solder. electrode is covered by new solder. Solder temperature : 230±5°C Duration : 4±1 sec. 13. Resistance to Soldering R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±2% Reflow soldering : Solder temperature : 240°C Duration : 5 sec. 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Conditions for 1 cycle 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Conditions for 1 cycle 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chandber. testing substrate : glass-epoxy-resin substrate 16. Damp Heat (steady state) R25 change : Within ±1% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Huridity : 85±5%RH Doration : 1000±12 hrs		1005 (0402)	1608 (0603)		
13. Resistance to Soldering R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Reflow soldering : Solder temperature : 40°C Duration : 5 sec. 14. Thermal Shock R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Conditions for 1 cycle 14. Thermal Shock R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Conditions for 1 cycle 15. High Temperature Life Test R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Temperature : 125±2° Duration : 1000±12 hrs Temperature : 125±2°C Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±1% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Temperature : 85±2° Huridity : 85±5%RH Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±1% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% Temperature : 85±2° Huridity : 85±5%RH	12. Solderability	At least 75% of terminal	At least 80% of terminal	According to JIS C5102 clause 8.4.	
13. Resistance to Soldering R25 change : Within ±3% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±1% R25 change : Within ±5% B constant change : Within ±2% Reflow soldering : Solder temperature : 240°C Duration : 5 sec. 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Conditions for 1 cycle Conditions for 1 cycle 14. Thermal Shock R25 change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Conditions for 1 cycle Conditions for 1 cycle 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C B Constant change : Within ±3% Temperature : 125±2°C B Constant change : Within ±1% 16. Damp Heat (steady state) R25 change : Within ±1% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C B Constant change : Within ±1% Temperature : 125±2°C B Constant change : Within ±1% 16. Damp Heat (steady state) R25 change : Within ±1% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±8%RH Within ±1% Temperature : 85±2°C Humidity : 85±8%RH Within ±1%		electrode is covered by new	electrode is covered by new	Solder temperature : 230±5°C	
B constant change : Within ±1% B constant change : Solder temperature : 240°C Within ±1% Within ±2% Solder temperature : 240°C Preheating temperature : 150°C Preheating temperature : 150°C 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% Within ±1% R25 change : Within ±3% B Constant change : Within ±3% Step 1 : Minimum operating temperature ±0 / -3°C 30±3 min Step 2 : Room temperature ±0 3 min Step 2 : Room temperature ±0 3 min Step 4 : Room temperature ±0 3 min Step 4 : Room temperature ±0 3 min Step 4 : Room temperature ±0 3 min Step 4 : Room temperature ±0 3 min Step 4 : Room temperature ±0 3 min Step 4 : Room temperature ±0 3 min Step 4 : Room temperature ±0 5 min Number of cycles : 5 B Constant change : Within ±5% B Constant change : Within ±5% B Constant change : Within ±3% R25 change : Within ±3% <td< td=""><td></td><td>solder.</td><td>solder.</td><td>Duration : 4±1 sec.</td></td<>		solder.	solder.	Duration : 4±1 sec.	
Within ±1% Within ±2% Duration : 5 sec. Preheating temperature : 150°C Preheating time : 90 sec. Number of reflows : 3 times 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Within ±1% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : B Constant change : Within ±1% R25 change : Within ±5% B Constant change : B Constant change : Within ±1% Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% B Constant change : B Constant change : Within ±1% B Constant change : B Constant change : B Constant change : B Constant change : B Constant change : <t< td=""><td>13. Resistance to Soldering</td><td>R25 change : Within ±3%</td><td>R25 change : Within ±5%</td><td>Reflow soldering :</td></t<>	13. Resistance to Soldering	R25 change : Within ±3%	R25 change : Within ±5%	Reflow soldering :	
14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Conditions for 1 cycle Step1 : Minimum operating temperature +0./-3°C 30±3 min Step2 : Room temperature 2 to 3 min Step3 : Maximum operating temperature +0./-3°C 30±3 min Step3 : Maximum operating temperature +0./-3°C 30±3 min Step3 : Maximum operating temperature +0./-3°C 30±3 min Step4 : Room temperature 2 to 3 min Number of cycles : 5 Recovery : 2 to 3 hrs of recovery under the standard condition after the test. 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Hermeture : 85±2°C Humidity : 85±5%RH 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±5%RH		B constant change :	B constant change :	Solder temperature : 240°C	
14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Conditions for 1 cycle Step1 : Minimum operating temperature +0/-3°C 30±3 min Step2 : Room temperature 2 to 3 min Step2 : Room temperature 2 to 3 min Step3 : Maximum operating temperature +0/-3°C 30±3 min Step2 : Room temperature 2 to 3 min Number of cycles : 5 Recovery : 2 to 3 hrs of recovery under the standard condition after the test. 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C B Constant change : Within ±5% B Constant change : Within ±3% Temperature : 125±2°C B Constant change : Within ±3% 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 85±2°C B Constant change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C B Constant change : Within ±5% B Constant change : Within ±3% Temperature : 85±2°C Humidity : 85±5%RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal for test chandber. testing substrate		Within ±1%	Within ±2%	Duration : 5 sec.	
14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Conditions for 1 cycle Step1 : Minimum operating temperature +0/-3°C 30±3 min Step2 : Room temperature 2 to 3 min Step2 : Room temperature 2 to 3 min Step4 : Room temperature 2 to 3 min Mumber of cycles : 5 Recovery : 2 to 3 hrs of recovery under the standard condition after the test. 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : glass-epoxy-resin substrate 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C B Constant change : Humidity : 85±5% RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber.				Preheating temperature : 150°C	
14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Conditions for 1 cycle 14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Conditions for 1 cycle 14. Thermal Shock R25 change : Within ±3% Within ±1% R25 change : Within ±3% B Constant change : Within ±1% Conditions for 1 cycle 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber. testing substrate 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate				Preheating time : 90 sec.	
14. Thermal Shock R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Conditions for 1 cycle 14. Thermal Shock R25 change : Within ±1% B Constant change : Within ±1% Conditions for 1 cycle 14. Thermal Shock B Constant change : Within ±1% B Constant change : Within ±3% Conditions for 1 cycle 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 86±2°C Humidity : 85±5%RH 16. Damp Heat (steady state) R25 change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 86±2°C Within ±3%				Number of reflows : 3 times	
Harmania biook Harmania biook B Constant change : Within ±1% B Constant change : Within ±3% Step1 : Minimum operating temperature +0/-3°C 30±3 min Step2 : Room temperature 2 to 3 min Step2 : Room temperature 2 to 3 min Number of cycles : 5 Recovery : 2 to 3 hrs of recovery under the standard condition after the test. 15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : glass-epoxy-resin substrate 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C B Constant change : Within ±3% 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 85±2°C Humidity : 85±5%RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber.				testing substrate : glass-epoxy-resin substrate	
Within ±1% Within ±3% Step2 : Room temperature 2 to 3 min Step2 : Room temperature 2 to 3 min Step3 : Maximum operating temperature +0/-3°C 30±3 min Step4 : Room temperature 2 to 3 min Step4 : Room temperature 2 to 3 min Number of cycles : 5 Recovery : 2 to 3 hrs of recovery under the standard condition after the test. 15. High Temperature Life Test R25 change : Within ±3% R25 change : Within ±5% Temperature : 125±2°C B Constant change : Within ±1% R25 change : Within ±3% R25 change : Within ±3% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : glass-epoxy-resin substrate 16. Damp Heat (steady state) R25 change : Within ±3% R25 change : Within ±3% Temperature : 85±2°C B Constant change : Within ±1% Within ±3% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs Humidity : 85±5% RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal	14. Thermal Shock	R25 change : Within ±3%	R25 change : Within ±5%	Conditions for 1 cycle	
15. High Temperature Life Test R25 change : Within ±3% Within ±1% R25 change : Within ±5% Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% R25 change : Within ±5% B Constant change : Within ±3% R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs		B Constant change :	B Constant change :	Step1 : Minimum operating temperature $+0/-3^{\circ}C$ 30±3 min	
15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±3% R25 change : Within ±5% B Constant change : Within ±3% Temperature : 125±2°C Duration : 1000±12 hrs 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : 1000±12 hrs		Within ±1%	Within ±3%	Step2 : Room temperature 2 to 3 min	
15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : glass-epoxy-resin substrate 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : 85±2°C				Step3 : Maximum operating temperature $+0/-3^{\circ}C$ 30±3 min	
15. High Temperature Life Test R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 125±2°C Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. testing substrate : glass-epoxy-resin substrate 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber.				Step4 : Room temperature 2 to 3 min	
15. High Temperature Life Test R25 change : Within ±3% R25 change : Within ±3% R25 change : Within ±5% Temperature : 125±2°C B Constant change : Within ±1% B Constant change : Duration : 1000±12 hrs Within ±1% Within ±1% R25 change : Within ±3% Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. 16. Damp Heat (steady state) R25 change : Within ±3% R25 change : Within ±3% R25 change : Within ±5% B Constant change : Within ±1% Within ±1% Temperature : 85±2°C Humidity : 85±5% RH Duration : 1000±12 hrs Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal				Number of cycles : 5	
15. High Temperature Life fest B Constant change : Within ±1% B Constant change : Within ±3% B Constant change : B Constant change : Within ±3% Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal from test chamber. 16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±5%RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal				Recovery : 2 to 3 hrs of recovery under the standard condition after the test.	
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16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C B Constant change : Within ±3%	5 ·····	B Constant change :	B Constant change :	Duration : 1000±12 hrs	
16. Damp Heat (steady state) R25 change : Within ±3% B Constant change : Within ±1% R25 change : Within ±5% B Constant change : Within ±1% Temperature : 85±2°C Humidity : 85±5%RH Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal		Within ±1%	Within ±3%		
B Constant change : B Constant change : B Constant change : Humidity : 85±5%RH Within ±1% Within ±3% Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal				testing substrate : glass-epoxy-resin substrate	
B Constant change : B Constant change : Humidity : 85±5%RH Within ±1% Within ±3% Duration : 1000±12 hrs Recovery : 2 hrs of recovery under the standard condition after the removal	16. Damp Heat (steady state)	R25 change : Within ±3%	R25 change : Within ±5%	Temperature : 85±2°C	
Recovery : 2 hrs of recovery under the standard condition after the removal		B Constant change :	B Constant change :	Humidity: 85±5%RH	
		Within ±1%	Within ±3%	Duration : 1000±12 hrs	
testing substrate : glass-epoxy-resin substrate				testing substrate : glass-epoxy-resin substrate	

Note on standard condition : "standard condition" referred to herein is defined as follows :

5 to 35 $^\circ C$ of temperature, 45 to 85% relative humidity and 86 to 106kPa of air pressure.

When there are questions concerning measurement results :

In order to provide correlation data, the test shall be conducted under condition of $20\pm2^\circ$ C of temperature, 60 to 70% relative humidity and 86 to 106kPa of air pressure.

Unless otherwise specified, all the tests are conducted under the "standard condition."